

In the Claims:

Please cancel claims 1-51, and add claims 60-70. Following is a complete listing of the claims pending in the application, as amended:

1-51. (Cancelled)

52. (Currently Amended) A microelectronic component testing system, comprising:

a substrate having a front face, a back face, and a plurality of openings extending from the front face to the back face in an array;

~~an intermediate layer on an inner surface of each opening;~~

an array of electrically isolated conductors patterned from an integral metal layer, each conductor having a contact end adjacent the front surface of the substrate, an intermediate length received in one of the openings in the substrate, and an exposed length extending outwardly beyond the back surface of the substrate a distance of no more than 200 microns; and

a backing member joined to the substrate and having a confronting surface oriented toward the substrate front surface, the confronting surface carrying a plurality of electrical contacts, each of which is electrically coupled to the contact end of one of the conductors.

53. (Original) The microelectronic component testing system of claim 52 wherein the substrate comprises undoped silicon.

54. (Original) The microelectronic component testing system of claim 52 wherein each of the conductors has a diameter no greater than 200 microns.

55. (Original) The microelectronic component testing system of claim 52 wherein each of the conductors has a diameter no greater than 60 microns.

56. (Original) The microelectronic component testing system of claim 52 wherein each of the conductors has a diameter of about 10-60 microns.

57. (Original) The microelectronic component testing system of claim 52 wherein the backing member comprises a flexible tape.

58. (Original) The microelectronic component testing system of claim 52 wherein the backing member comprises a printed circuit board.

59. (Original) The microelectronic component testing system of claim 52 further comprising a controller and a power supply, the controller being operatively connected to the backing member to monitor test performance of a microelectronic component.

60. (New) The microelectronic component testing system of claim 52 further comprising an intermediate layer disposed between an inner surface of one of the openings in the substrate and the conductor received in that opening.

61. (New) The microelectronic component testing system of claim 60 wherein the intermediate layer provides electrical insulation between the substrate and the conductor received in that opening.

62. (New) The microelectronic component testing system of claim 60 wherein the intermediate layer extends across at least a portion of the front face of the substrate.

63. (New) A microelectronic component testing system comprising:
a probe card including:
a substrate having a front face, a back face, and a plurality of openings
extending from the front face to the back face in an array;

an array of electrically isolated conductors patterned from an integral metal layer, at least one of the conductors having a contact end adjacent the front surface of the substrate, an intermediate length received in one of the openings in the substrate, and an exposed length extending outwardly beyond the back surface of the substrate a distance of no more than 200 microns; and

a backing member joined to the substrate and carrying a plurality of electrical contacts, at least one of which is electrically coupled to the contact end of the at least one conductor;

a power supply; and

a controller in communication with the probe card and the power supply, the controller being configured to monitor test performance of a microelectronic component.

64. (New) The microelectronic component testing system of claim 63 wherein the substrate comprises undoped silicon.

65. (New) The microelectronic component testing system of claim 63 wherein the at least one conductor has a diameter no greater than 200 microns.

66. (New) The microelectronic component testing system of claim 63 wherein the at least one conductor has a diameter no greater than 60 microns.

67. (New) The microelectronic component testing system of claim 63 wherein each of the conductors has a diameter of about 10-60 microns.

68. (New) The microelectronic component testing system of claim 63 wherein the backing member comprises a flexible tape.

69. (New) The microelectronic component testing system of claim 63 wherein the backing member comprises a printed circuit board.

70. (New) The microelectronic component testing system of claim 63 further comprising a controller and a power supply, the controller being operatively connected to the backing member to monitor test performance of a microelectronic component.